



喬訊電子工業股份有限公司
 CHYAO SHIUNN ELECTRONIC INDUSTRIAL LTD.
 7FL., NO.17, LANE 3, SEC.1 CHUNG CHENG EAST RD.,
 TAMSHUI, TAIPEI, TAIWAN, R.O.C.
 TEL: 886-2-2629-9955 (REP) FAX: 886-2-2626-6677



http://www.chyaoshiunn.com.tw E-mail:cs@chyaoshiunn.com.tw

Type Document	Product Specification	Revised /Edition	D
Date Issued	2010/01/29	Data Revised	2013/11/28
Subject : JS-1201-XX JS-1201-T/TG JS-1201-XXXX JS-1202-XXXXXX Pitch 1.20mm SMT Series Wire to Board Connector for DC Power Supply			Issued By: Engineering Dept.

This specification is referred to 1.20mm SMT series wire to board connector for power supply.

本規格書內容係提供 1.20 mm SMT 系列產品相關參考，
其用途為電線端相接於電路板端動力電源連接器

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- 1.0 Product Name/Part Number & Drawing Number.(產品名稱 / 產品型號及圖面型號)
- 2.0 Construction/Dimensions/Material & Surface Finish.(材質以及表面鍍層)
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- 9.0 Insertion Force (I.F.) & Withdrawal Force (W.F.) for user reference (插入力與拔出力參考規格)
- 9.0 Remark (備註).

REV. (版本)	Revision Record (改版變更原因)	Date(日期)	EC No
B	鹽水噴霧週期以電鍍方式區隔為 8 小時與48 小時；	2011/05/24	EC2011-05-051
C	1.增加耐久性 2.刪除硫化氫 3.修正(EIA-364) 參考規範 4.修改 9.1 Table 1 Insertion Force (I.F.) & Withdrawal Force (R.F.) for user reference 5.增列額定電壓 6.修改端子鍍層敘述	2012/08/22	EC2012-08-015
D	修訂 Solder Ability 附註 Tin Plated : 95% / Gold Plated : 75%	2013/11/28	EC2013-11-028



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1.0 Product Name/Part Number & Drawing Number(產品名稱 / 產品型號及圖面型號): Note: (xx) The number of the circuits.

Product Name(產品名稱)	Part Number(零件型號)	Drawing Number(圖面型號)
Crimp Terminal	JS-1201-T2 / JS-1201-TG0	
Housing	JS-1201-XX-NA-XX / JS-1201-XX-BK-NH	
Wafer	JS-1202-XXG0-BKNH / JS-1202-XXXX-BKNH / JS-1202-XXG0-NAXX / JS-1202-XXXX-NAXX	

2.0 Construction/Dimensions/Material & Surface Finish(材質以及表面鍍層):

Part Name(零件名稱)	Material(材質)	Surface Finish(表面鍍層)
Crimp Terminal (柳壓端子)	Phos.Phos Bronze C5210	Tin Plated
		Gold Plated
Housing(電線端連接器)	Nylon 66 with 30% Glass Fiber	UL 94V-0 ; Color : Nature
	Nylon 66 with 30% Glass Fiber(Halogen Free)	UL 94V-0 ; Color : Black
Wafer (電路板端連接器)	Contacts (導體)	Gold-Plated / Tin- Plated
	Solder Nail (接地片)	Tin- Plated
	Base(膠座)	Nylon-9T
Nylon 6T/66(Halogen Free)		UL 94V-0 ; Color : Black

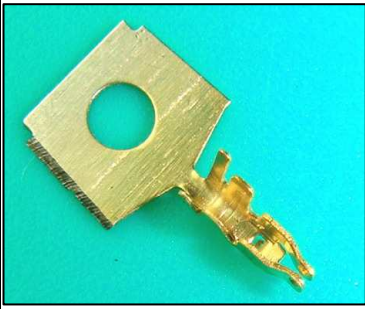
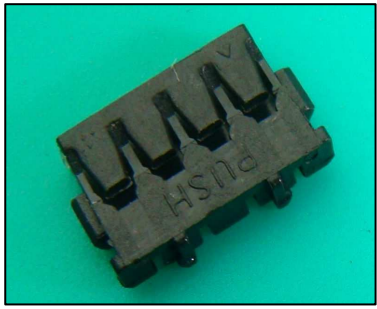
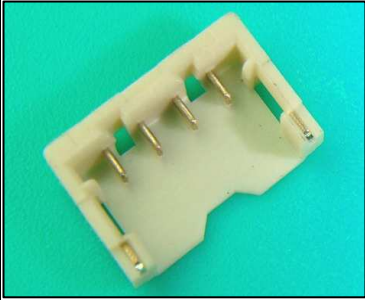
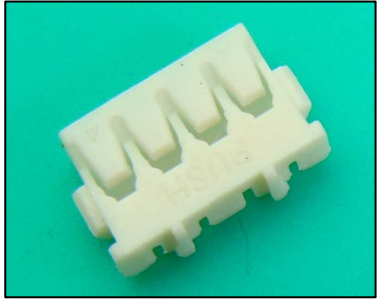
3.0 Characteristic(產品特性):

Item(項目)	Standard(標準規範)		
3.1 額定電流 Rated Current		AWG #28	AWG #30
	2 Circuit	2.0A AC/DC	1.0A AC/DC
	3 Circuit	2.0A AC/DC	1.0A AC/DC
	4 Circuit	1.5A AC/DC	1.0A AC/DC
3.2 額定電壓 Rated Voltage	50 V AC/DC		
3.3 Ambient Temperature Range 環境與操作溫度範圍	(操作使用溫度範圍) Operating Temp.: -25°C~+85°C		
	Including 30°C Terminal Temperature Rise at rated Current , (包括定額電流內, 端子所產生 30°C 以下溫昇) (置存於環境當中溫度與濕度範圍) Non - Operating Temp. : -25°C~+85°C ; 90% R.H. Max		
3.4 Applicable Wire 適用電線	3.4.1 (金屬導體型號) Conductor Construction Size: AWG #28~#30		
	3.4.2 (電線絕緣材質外徑) Wire Insulation O.D.: 0.50mm~0.63mm		
3.5 Applicable Printed Circuit Board Layout 適用電路板佈局設計	3.5.1 SMT Layout: 1.20 ± 0.05 mm per Pitch 表面黏著焊錫點之間距		
	3.5.2 SMT Layout: 0.85X0.60±0.05 mm for Pin Post 導體焊錫點面積		
	3.5.3 SMT Layout: 0.70X0.80±0.05 mm for Solder Nail 接地片焊錫點面積		



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4.0 Specimen(樣本圖示) :

Part Name / Part Number / Picture or Photograph 零件名稱 / 零件型號 / 樣本圖示			
Crimp Terminal JS-1201-TXX JS-1201-TGX		Housing JS-1201-XX-BK-NH	
Wafer JS-1202-XXXX-XXXX		Housing JS-1201-XX-XX-XX	

5.0 Applicable Standards(適用規範):

ANSI/EIA 364 ; EIA/ECA 364 Testing method for electrical connectors.

電子連接器，所適用之 ANSI/EIA 364 ; EIA/ECA 364 測試規範

6.0 Mechanical Performance(機械性能):

Item(項目)	Test Condition(測試條件)	Requirement(規格)
6.1 Insertion & Withdrawal Force 嵌入力與拔出力	A socket with correctly terminated wires and a header shall be mated and unmated on the mating axis. Initial insertion and withdrawal forces and withdrawal force at 30 times shall be measured. (testing speed : 1 to 5 mm/sec) (EIA 364-13D) 將埋入電線之連接器膠座，以每秒 1 至 5mm 速率，與電路板端連接器連續進行 30 回嵌合與拔出往返測試，並量測首回與 30 回之後拔出力	Refer to 9.1 Table1. 參照第 9.1 項 表格 1



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Item(項目)		Test Condition(測試條件)	Requirement(規格)
6.2	Wire Retention Force 電線脫離端子之拔出力	Pulling load shall be applied between a correctly crimped contact and wire. The load required to pull the wire out of the contact or break the wire shall be measured. (Test speed: 25mm/min.) 先以電線末端採正確方式包覆端子，而後以每分鐘 25mm/min 速率，測試電線脫離端子包覆，或者未脫離端子包覆電線即斷裂，並量測其最終拔出力	AWG#30 0.5kgf(Min.) 最小容許值
			AWG#28 1.0kgf(Min.) 最小容許值
6.3	Crimp Terminal Retention Force (in Housing) 鍍線端子與膠座之間拔出力	Axial pullout force on the terminal in the housing at the speed rate of 1 to 5 mm/sec 對於已經存在於膠座當中鍍線端子，施以每一秒 1 to 5 mm 速率之軸向拔出力	(When AWG#28 is applied.) 單一接觸點 Per Contact 最小容許值 0.4kgf(Min.)

7.0 Electrical Performance(電氣性能) :

Item(項目)		Test Condition(測試條件)	Requirement(規格)
7.1	(Low -Signal Level) Contact Resistance (低階信號) 接觸阻抗	A maximum voltage of 20mV and a maximum current of 10mA are applied to the mate connector. (EIA/ECA 364-23C) 對組合狀態下連接器，於其兩端施以最大測試電壓 20mV 以及最大測試電流 10mA (Does not include wire resistance 不包含電線阻抗)	Contact Resistance: 10 milliohms Max. 最大容許值. 10m 歐姆
7.2	Insulation Resistance 絕緣阻抗	Apply 500V D/C for 1 minute between adjacent contacts to measure the insulation resistance. 對相鄰兩接觸導體，於一分鐘時間內施予 500V D/C 電壓，並量測其間絕緣阻抗值 (EIA 364-21C)	Insulation Resistance: Initial 100 megohms Min 最初容許值. 100 M 歐姆



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Item(項目)	Test Condition(測試條件)	Requirement(規格)
7.3 Withstanding Voltage 耐電壓	Apply 500V A/C (rms) for 1 minute and the leakage current shall not exceed 0.5mA to the adjacent terminal and ground of the mate connectors. (EIA 364-20C) 對組合狀態下連接器，於其相鄰兩導體末端各施以電壓 500V A/C(實效值) 時間 1 分鐘，且漏電流必須小於 0.5mA(毫安培)	No breakdown or flashover. 無損毀或者產生火花

8.0 Environmental Performance(環境性能) :

Item(項目)	Test Condition(測試條件)	Requirement(規格)
8.1 Durability 耐久性	Mate Connectors up 30 Cycles at a Maximun rate of 10 cycles Per minute prior to environmental test 以組合狀態下連接器且未經環境測試，依每分鐘內進行 10 次嵌入與拔出之最大速率，連續 30 次嵌入與拔出往返測試 (EIA/ECA 364-09C)	(After the test) Contact resistance : 經耐久性試驗後接觸阻抗 : 20 mΩ Max
8.2 Vibration 耐振動	A mated connector shall be mounted on a printed Circuit board and subjected to a vibration test of the following conditions. During the test, test current continuity shall be checked. After the test, contact resistance shall be measured. 以組合狀態下連接器焊接於電路板作為試驗樣品,依照隨附如下規格要求,進行耐振動試驗，試驗過程中確認是否產生不連續電流(斷電)現象，並於試驗過後量測其接觸阻抗。 (EIA/ECA 364-28E-Condition I) Frequency(頻率) : 10~55~10 Hz/minute. Amplitude (振幅) : 1.5 mm P-P Direction (方向) :1. Axis of up and down.上下軸向(Y 軸) 2. Axis of right the left. 左右軸向(X 軸) 3. Axis of front and back.前後軸向(Z 軸) Period(週期) : 2 hours for each direction. (每一個軸向持續 2 小時)	Initial Contact Resistance : 10 milliohms Max. 接觸阻抗最初容許值: 10m 歐姆 (After the test) Contact Resistance: 20 milliohms Max. 經耐振動試驗後接觸阻抗 : 最大容許值 20m 歐姆 No discontinuity current is longer than 1 microsecond. 電流中斷現象， 時間不可多於1微秒



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Pitch 1.20mm SMT Series Wire to Board Connector for DC Power Supply			

Item(項目)		Test Condition(測試條件)	Requirement(規格)
8.3	Humidity (Steady State) 恆溫恆濕	<p>A mated connector shall be placed in a humidity chamber of the following conditions. After the test, the contact resistance, the insulation resistance and the dielectric withstanding voltage shall be measured.</p> <p>(EIA 364-31B Conditions III. Method A)</p> <p>以組合狀態下連接器放置於恆定溫度與濕度的空間，依照隨附如下規格要求，進行恆溫恆濕試驗，並於試驗過後量測其接觸阻抗、絕緣阻抗、以及耐電壓測試。</p> <p>Temperature(溫度) : 40±2°C.</p> <p>Relative Humidity(相對濕度) : 90%~95% (RH).</p> <p>Period(週期) : 96 hours continuously. (持續 96 小時)</p>	<p>(After the test)</p> <p>Contact Resistance:</p> <p>20 milliohms Max.</p> <p>經恆溫恆濕試驗後接觸阻抗： 最大容許值. 20m 歐姆</p>
			<p>(After the test)</p> <p>Insulation Resistance :</p> <p>100 Megohms Min.</p> <p>經恆溫恆濕試驗後絕緣阻抗： 最小容許值. 100 M 歐姆</p>
			<p>(After the test)</p> <p>Withstanding Voltage :</p> <p>300V AC</p> <p>經恆溫恆濕試驗後耐電壓：</p>
8.4	Thermal Shock 冷熱衝擊	<p>A mated connector shall be subjected to a thermal shock test of the following conditions. After the test, the contact resistance, the insulation resistance and the dielectric withstanding voltage shall be measured.</p> <p>以組合狀態下連接器作為試驗樣品，依照隨附如下規格要求，進行冷熱衝擊試驗，並於試驗過後量測其接觸阻抗、絕緣阻抗、以及耐電壓測試。</p> <p>(EIA/ECA 364-32D Conditions I. Method A)</p> <p>One Cycle Consists Of:</p> <p>-55 +0/-3°C for 30 minutes. → Room Temp.5 minutes</p> <p>85+3/-0°C for 30 minutes. → Room Temp.5 minutes</p> <p>Total Cycles: 5 Cycles.</p> <p>以-55+0/-3°C溫度持續 30 分鐘，經室溫 5 分鐘，而後再以 85+3/-0°C溫度持續 30 分鐘，再經室溫 5 分鐘，構成一次冷熱循環，總計循環次數 5 次。</p>	<p>Same as paragraph 8.3</p> <p>同 8.3 章節</p>



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Item(項目)	Test Condition(測試條件)	Requirement(規格)
8.5 Heat Aging 高溫老化試驗	A mated connector shall be placed in a heat oven of the following conditions. After the test, contact resistance shall be measured. (EIA 364-17B Conditions III . Method A) 以組合狀態下連接器放置於加熱烤箱當中, 依照隨附如下規格要求, 進行高溫老化試驗, 並於試驗過後量測其接觸阻抗。 Temperature(溫度): 85±2℃. Period(週期): 96 hours continuously.(持續 96 小時)	Initial Contact Resistance : 10 milliohms Max. 接觸阻抗最初容許值:10m 歐姆 (After the test) Contact Resistance : 20 milliohms Max. . 經高溫老化試驗後接觸阻抗 :
8.6 Salt Spray 鹽水噴霧	A mated connector shall be subjected to a Salt Spray test of the following conditions. After the test , the specimen shall be washed with running water and dried naturally before the measurement of contact resistance. 以組合狀態下連接器作為試驗樣品, 依照隨附如下規格要求, 進行鹽水噴霧試驗, 試驗過後將樣品用清水沖洗並經過自然風乾, 而後量測其接觸阻抗。 (EIA 364-26B Conditions B) Density(鹽水密度): 5 % in weight. Temperature(溫度): 35±2℃. Period(週期): Terminal or contact (Stamping after tin plated for 8 hours) ; Terminal or contact (Stamping before tin plated for 48 hours) 端子或導體(先電鍍後沖壓 8 小時) ; 端子或導體 (先沖壓後電鍍 48 小時)	Initial Contact Resistance : 10 milliohms Max. 接觸阻抗最初容許值:10m 歐姆 (After the test) Contact Resistance: 20 milliohms Max. 經鹽水噴霧試驗後接觸阻抗 : 最大容許值. 20m 歐姆
8.7 Solder Ability 焊錫性	Fluxed soldering section of header shall be dipped in solder of the following conditions. (EIA 364-52B) 將連接器 pin 針基板嵌入端, 接觸熱溶狀錫料, 依照隨附如下規格要求, 進行焊錫性試驗 Solder Temperature (焊錫溫度) : 245 ± 5℃. Immersion Period (沉浸週期) : 3±0.5 Seconds (操作方式) : 零件焊錫位置, 距離導體以及固定片末端 0.5mm Method : 0.5mm from contact tip and solder nail tip	Solder entirely (Tin Plated : 95% / Gold Plated : 75%) of immersed area must show no voids or pinholes. 焊料覆蓋面積必須達到 (鍍錫 95% / 鍍金 75%), 而且不能產生氣孔或空隙

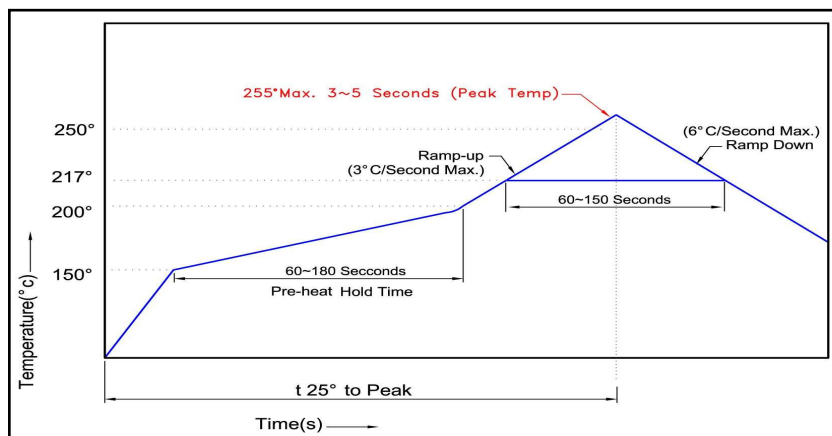


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Item(項目)	Test Condition(測試條件)	Requirement(規格)
8.8 Resistance To Soldering Heat 焊錫耐熱性	By reflow soldering 迴焊適用溫度範圍 : Refer to Temperature Profile 請參考 8.8.1 溫度曲線圖 By soldering iron 手工烙鐵焊錫適用溫度範圍 : 350 ± 5°C 3±0.5 Seconds. (操作方式) : 零件焊錫位置 , 距離導體以及固定片末端 0.5mm Method : 0.5mm from contact tip and solder nail tip (EIA/ECA 364-56C Procedure 3. Conditions A)	No deformation or damage. 不可有變形或損壞

Notes : Flowing Mixed Gas (EIA 364-65A) shall be conduct by Customer request 混合流動氣體測試依照客戶需求

8.8.1 Temperature Profile(溫度曲線圖) :



9.0 Tables & Attachments

9.1 Table 1. Insertion Force (I.F.) & Withdrawal Force (W.F.) for user reference:

No. Of Circuits 極數	AT INITIAL 首次嵌入與拔出(初始值)		AT 30 TH 30 次嵌入與拔出之後
	I.F. (MAX) 嵌入力	W.F. (MIN) 拔出力	W.F. (MIN) 拔出力
	02	1.2	0.25
03	1.8		
04	2.4		

Unit : Kg/f

10.0 Remark(備註) : Any change or revision for the product specification will not be announced in advance.

Please contact our sales representative for the latest information.

有關規格書內容經變更或改版, 如未能夠及時發佈與通知, 煩請連絡我司業務人員以提供產品最新資訊

Reviewed: J.M.Chang Approved: Peter Chang Verified: Indiana Huang



Date Issued	2013/05/17	Revised /Edition	C
Title of Document	HANDLING MANUAL		Issued By: Engineering Dept.
Title Subject	Pitch 1.20mm (Dual Row) Wire to Board Connector for power supply JS-1201-T JS-1201 JS-1202		

This manual describes important and required points of handling about connector . Be sure to read this manual thoroughly before using connector.

*此操作手冊係說明連接器使用時必須注意的重點事項，
務必詳加閱讀內容之後，再行使用本產品*

1.0 Harness Assembly Operation 線材組裝作業

Terminal Mating 端子組裝

1.1 When you hold the wire at a further position, the wire would bend easily, making it difficult to insert the terminal.

當握持電線距鉗壓部位過遠的位置，電線容易彎曲下垂，使得它不易將端子嵌入膠座。

※ Please hold the cable at a 10mm distance from the crimped section.

請在距離鉗壓處 10mm 的位置握持電線。(see figure 1.1)

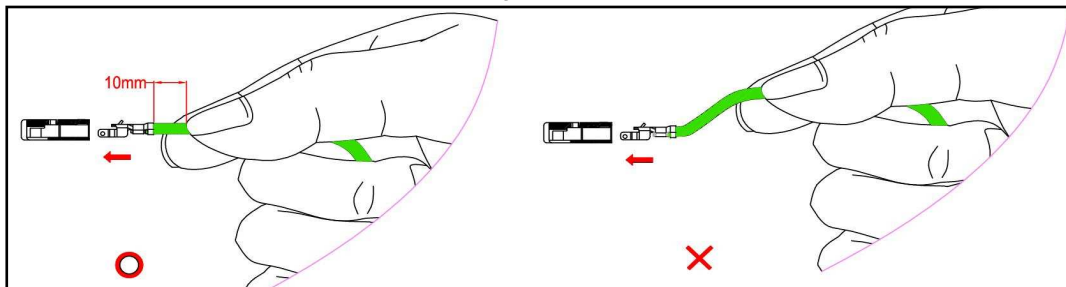


figure 1.1

※ The value (10mm) is a reference. It changes regards to the wire size and material. Please confirm the best position before starting the insertion.

10mm 僅供參考，視電線的尺寸大小及材質而有所改變，並在嵌入前確認合適的位置。

※ Please crimp the terminal using the specified height and width.

(Refer to crimp specification JS-1201-T)

端子鉗壓請依照規範之高度與寬度使用。(參考 JS-1201-T 端子壓著規格書)

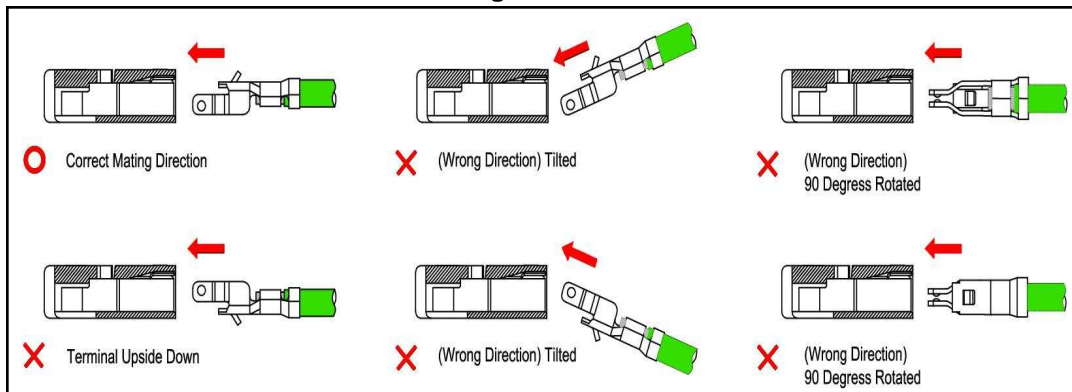
1.2 When insertion cannot be done smoothly, do not force the terminal to mate the connector. Please reconfirm if there is no deformation in the plastic or the terminal and re-insert.

當端子嵌入膠座不順暢，切勿使力將端子嵌入膠座，請先確認端子或膠座是否變形損壞然後再行嵌入組裝。

※ Please be careful on the direction of the terminal insertion. When the terminal is inserted in the wrong direction, it could lead to terminal deformation or plug housing breakage. (see figure 1.2)

請於端子嵌入膠座的同時仔細確認其方向，當端子嵌入方向錯誤，會導致端子變型損壞以及膠座破損

figure 1.2





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- ※ These crimped contacts should be absolutely straight and, without the use of extreme force, inserted in one operation into the contact cavities until a “click” is audible. (300g~500g forces is recommended) (see figure 1.2.1)
施予適度的力量將端子不偏不倚的嵌入膠座，直到端子彈片卡合定位聽見“喀嚓”聲為止。
(建議嵌入力 300 克~500 克 之間)。

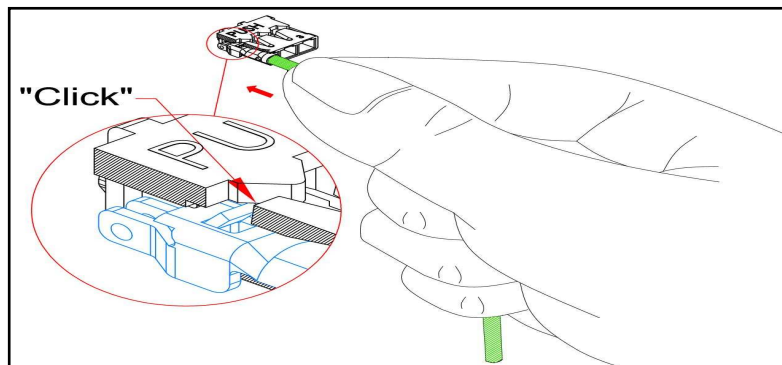


figure 1.2.1

- 1.3 Confirm if the terminal is inserted correctly by pulling the terminals with little force (100g). Do not pull hard. 當端子嵌入膠座之後，試著以少於 100g 的力量輕微拉動端子，切勿過度使力拉動端子，以此方式確認端子嵌入位置是否正確。
- ※ Misalignment of the crimped contacts should be avoided because of possible bending of the retention springs, and therefore impaired contact retention in the contact cavity. (see figure 1.3)
端子嵌入膠座其彈片卡合未達定位，可能使彈片變形，進而導致端子拔出力大幅衰減。

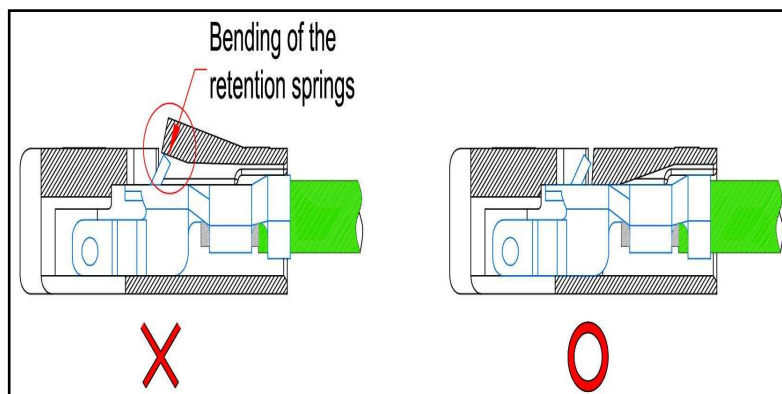


figure 1.3

- ※ When the terminal is not loaded fully, the terminal would fall out of the Housing
當端子嵌入膠座未完全定位，端子容易自膠座鬆脫。
- 1.1.4 When checking after terminal insertion, do not pull or bend the wire too much. The unanticipated force to the connector may lead to contact failure.
當確認端子已確實嵌入膠座，勿過度拉扯或彎曲電線，可能使電流通失效。
- 1.1.5 Please use the defined mating connector when you check the continuity. Mating with the wrong connector may lead to terminal deformation and contact failure.
組裝前請先行確認所搭配之連接器膠座，是否為同款系列之產品，錯誤搭配不屬同款的連接器，將導致端子變形損壞，電流通失效。



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2.0 Handling Precautions for SMT 使用表面黏著須知：

2.1 Reflow Soldering Method 迴焊使用方法：

Soldering should be conducted at the temperature below the temperature profile shown in product Specification as item of “Resistance to soldering heat “
 迴焊所適用溫度條件，參照規格書“焊錫耐熱性”項目中所示溫度曲線圖。
 Though recommended reflow temperature condition varies depending on solder paste to be used, evaluate and find adequate condition before production.
 迴焊建議溫度僅為參考，溫度條件的變化亦取決於錫膏的使用，視實際使用需求而作調整。
 Depending on the soldering condition, solder and flux wicking may occur on this connector. Check no problem in customer soldering condition before the use.
 錫膏毛細現象，攸關迴焊條件良窳，有可能造成連接器使用時溢錫、爬錫之發生。
 迴焊所需具備之條件，應先確認無誤之後，再行使用本產品
 Considering Handling of this connector in mating operation, tenacious heat-resistant resin is used for this connector. But ‘Blister’ may generate on the outer surface of the housing during the process of reflow soldering, depending on the condition of moisture absorption of the housing and the condition of reflow soldering. However, because ‘blister’ is not caused by decomposition of resin, it does not affect the performances of the connector.
 連接器所採用具剛性且耐高溫之塑膠，經迴焊製程可能會在連接器表面產生氣泡，其生成的原因源自於塑膠過度吸濕以及迴焊製程條件優劣，然而氣泡並不會對於塑膠產生侵蝕的作用，而且就連接器組裝使用功能性而言並不影響。
 There is no influence in the product performance though discoloration might be generated in the resin according to reflow condition.
 迴焊製程亦可能引起塑膠色澤變化，但不影響產品功能。

2.2 About whisker growth prevention for this product 關於避免錐鬚的生成

The Lead-Free plating of this product has been performed by re-flow matte-tin or gold plating which ensures maximum effectiveness for retarding whisker growth. It fully comply with JEDEC-JP002-(Current Tin-Whiskers Theory and Mitigation Practices Guideline.)
 此產品經採用無鉛鍍霧錫或鍍金施行於迴焊製程，已確認其對於延緩錐鬚生長可發揮最大效用。此方式完全符合 JEDEC-JP002 規範（當前通用的錐鬚理論和緩解實例指導方針）。

2.3 Connector Placement 連接器定位

Machine placement of the connector is recommended due to the inherent difficulty of manually placing fine-pitch connectors. The top surface of the connector housing has a flat area in the center to facilitate vacuum pick-up and handling. To avoid damage, the connectors should be picked up directly out of the embossed-tape packaging by the pick-up device. The placement machine is used to position the connectors to minimize the possibilities of damage that could result from improper handling.
 細距連接器經由手工置件定位極富難度，建議以機械方式置件定位取代，機械方式置件定位，可降低因操作不當而導致連接器損壞的情形發生。連接器表面平坦處且位於整體中心位置，較易於真空取件作業。真空取件應以垂直起降方式，將零件由包裝載帶取出，並避免損壞連接器。
 Placement of the connectors may be done by hand; however, extreme caution must be used when handling connectors to prevent deformation and contamination of the solder tines and hold-downs. 某些情況下可能以手工置件定位，尤特別謹慎避免連接器沾污、以及過度施力損壞連接器金屬導體末端焊錫區域。

2.4 Coplanarity 金屬導體與焊錫區域共面度：

Optimally, the connector contact solder tines should be centered on the PC board Pads. however, misregistration is permissible for some performance classifications.(See Figure 2.4)
 連接器金屬導體安放之最佳位置應座落於印刷電路板各相對應腳位之焊錫區域之中心線，然而對於有些效能特性之分類，可允許對位落差。



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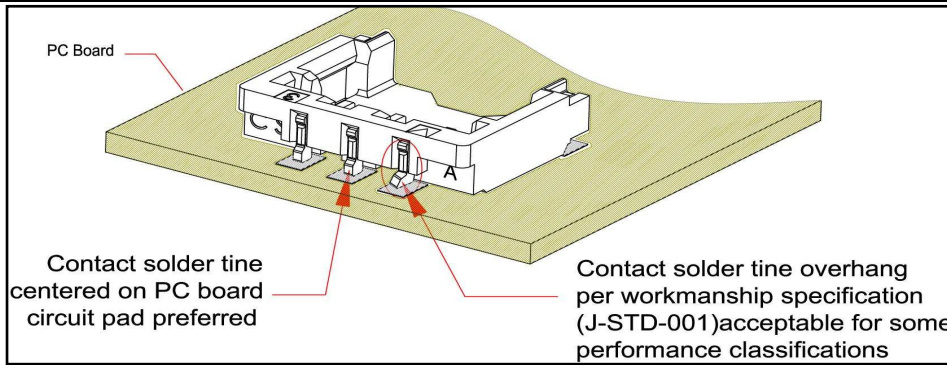


Figure 2.4

2.5 Solder Iron Method 手焊使用方法：

When soldering or re-soldering connector on PC board , below the temperature shown in product Specification as item of “ Resistance to soldering heat “

電路板上連接器使用手工焊錫或者是重焊 所適用溫度條件，參照規格書“焊錫耐熱性”項目中所建議溫度。Do not apply external force by pressing soldering iron tip on contact solder tail part. 切勿以過度的力量，將烙鐵尖端重壓導體末端焊錫區域。

If done, dismount and exchange connector. Do not reuse dismantled connector. 如以手焊方式卸除連接器應將其更換，切勿重覆使用已卸除之連接器。

3.0 Recommended Insertion 連接器嵌入組合建議使用方式

3.1 During mating process, if incase the Housing is angle mated towards the wafer of mating entrance In allow angle must not exceed 5°. (see figure 3.1)

當嵌入組合的同時，線端連接器如傾斜嵌入板端連接器，其所能容許的角度不可超過5度。

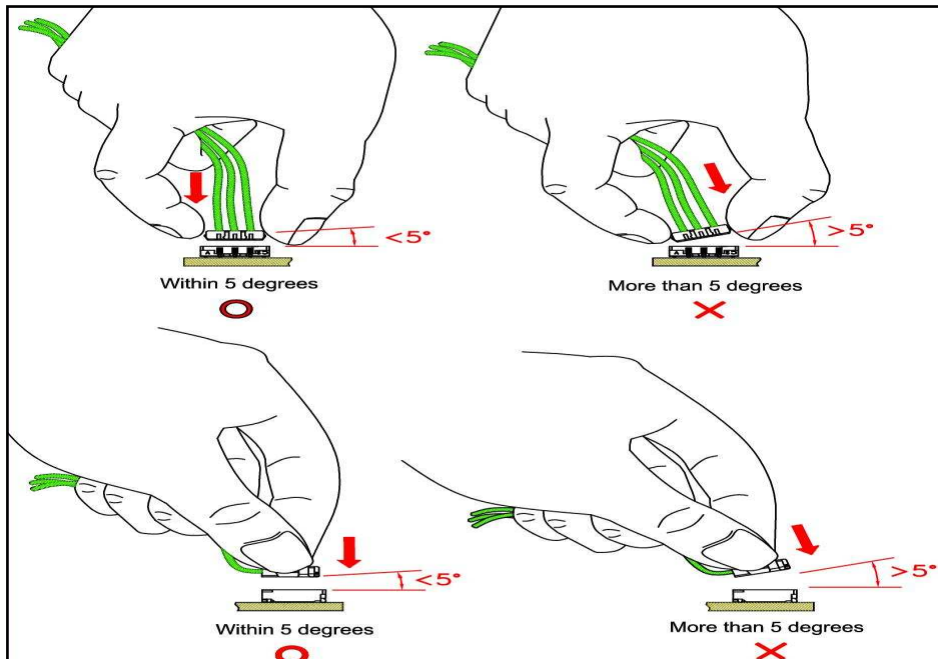


figure 3.1



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3.2 Mate a housing on the mating axis to a wafer. Later in time, confirm that the part of "PUSH" of the housing is pushed and it mates securely.(see figure 3.2)
 將線端連接器沿著與板端連接器互配之軸向作組合，隨後確認線端連接器外觀所標示"按壓"位置，並依照所指定位置將其壓入，使其與板端連接器完全密合。

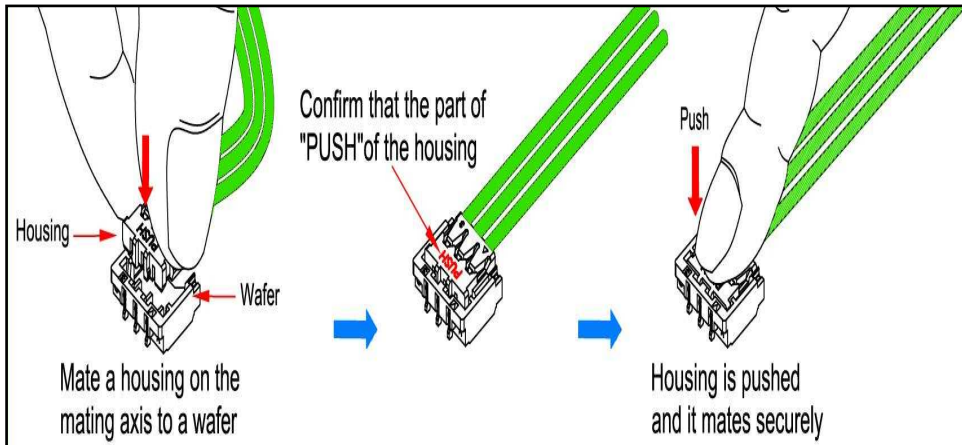


figure 3.2

※Besides, after mating operation, check that there is no inclining between wafer and housing, because such inclining may lead discontinuity of connector. (see figure 3.3)
 此外，嵌入組裝之後須確認線端連接器與板端連接器之間沒有傾斜，傾斜可能使電氣導通失效。

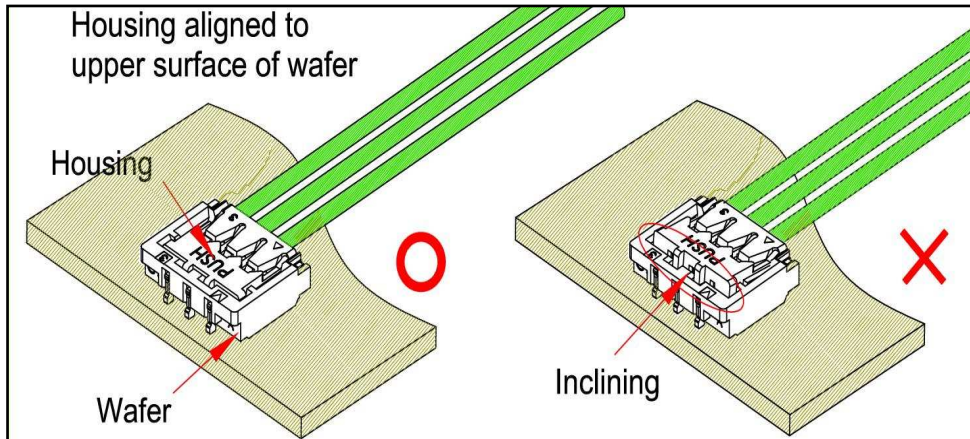


figure 3.3

4.0 Recommended removal 卸除連接器建議使用方式

4.1 Please hold all wires equally to prevent excessive force on certain wires. excessive force on certain wires or unmated horizontally could lead to damage. (see figure 4.1)
 請將握持電線的力量均勻分佈於每條電線，避免過度施力於某幾條電線或者以平行於電路板之軸向拔出連接器，皆可能導致連接器損壞。



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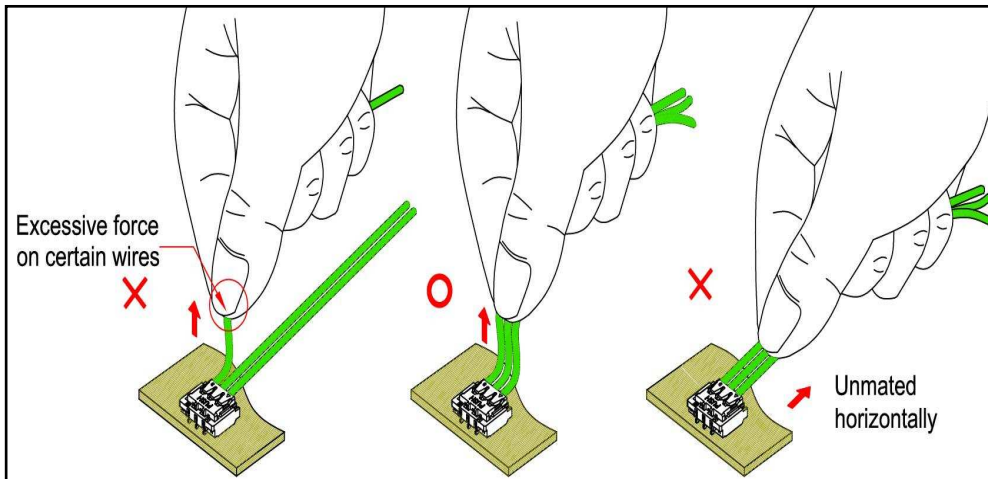


figure 4.1

4.2 Even in the case of unmating on mating axis, the same action as that of unmating in any angles may generate in condition that several tips of wires are held (wires aren't held in a bundle). In unmating the connector, be sure to hold the wires in a bundle within 15 degrees to the mating axis. (see figure 4.2)
甚至在連接器裝入軸上施行拔除動作時，若不依照適當角度而任意拔除，會使線材前端承受極大的拉力(在線材未細綁成束的狀況下)。在拔除連接器時，務必先握住線材成束後，並與連接器保持同軸，線材折彎角度要在同軸角度的 15 度內進行。

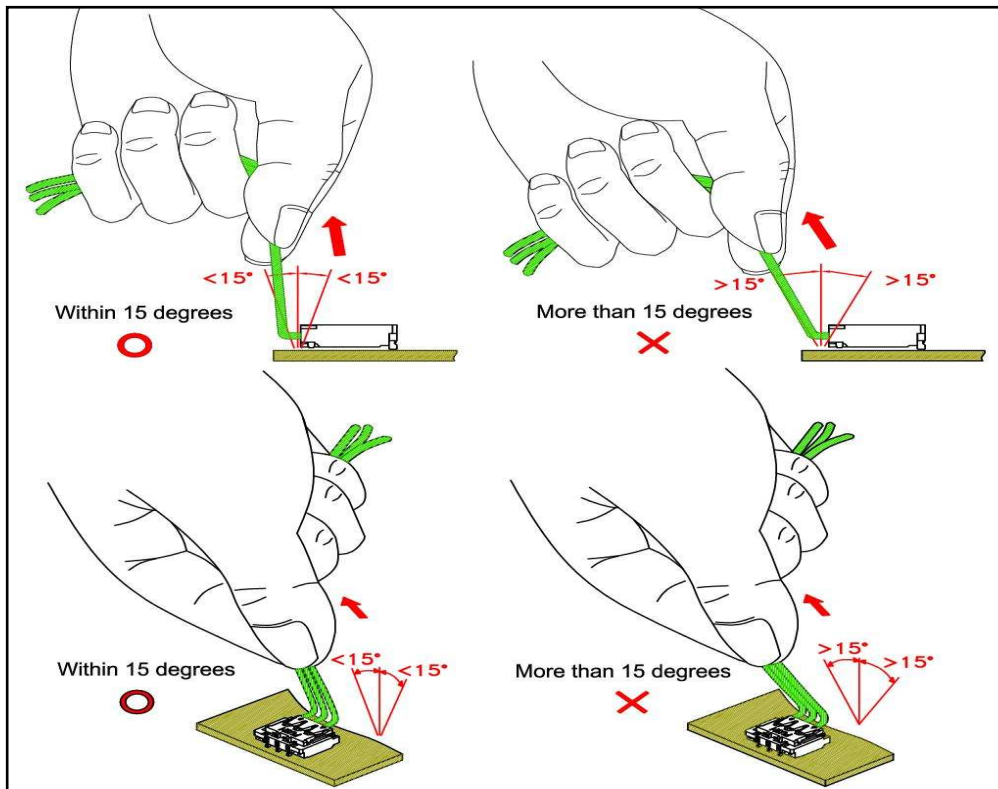


figure 4.2



喬訊電子工業股份有限公司
CHYAO SHIUNN ELECTRONIC INDUSTRIAL LTD.
7FL., NO.17, LANE 3, SEC.1 CHUNG CHENG EAST RD.,
TAMSHUI, TAIPEI, TAIWAN, R.O.C.
TEL: 886-2-2629-9955 (REP) FAX: 886-2-2626-6677



http://www.chyaoshiunn.com.tw E-mail:cs@chyaoshiunn.com.tw

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5.0 Handling of wire after mounting connector on PC Board:

連接器於電路板裝載完成，後續線材配置方式

5.1 Conduct wire handling carefully so that tension stemmed from wire bending is not loaded. Provide space above connector in order to form wire by bending and do not apply tension to connector as below. (see figure 5.1)

電線承受過度的彎折會引起緊縮的張力，因此電線所處的位置應謹慎妥善的配置。連接器周圍應具備足夠空間可供電線作適當彎折，以避免其產生張力承載於連接器。

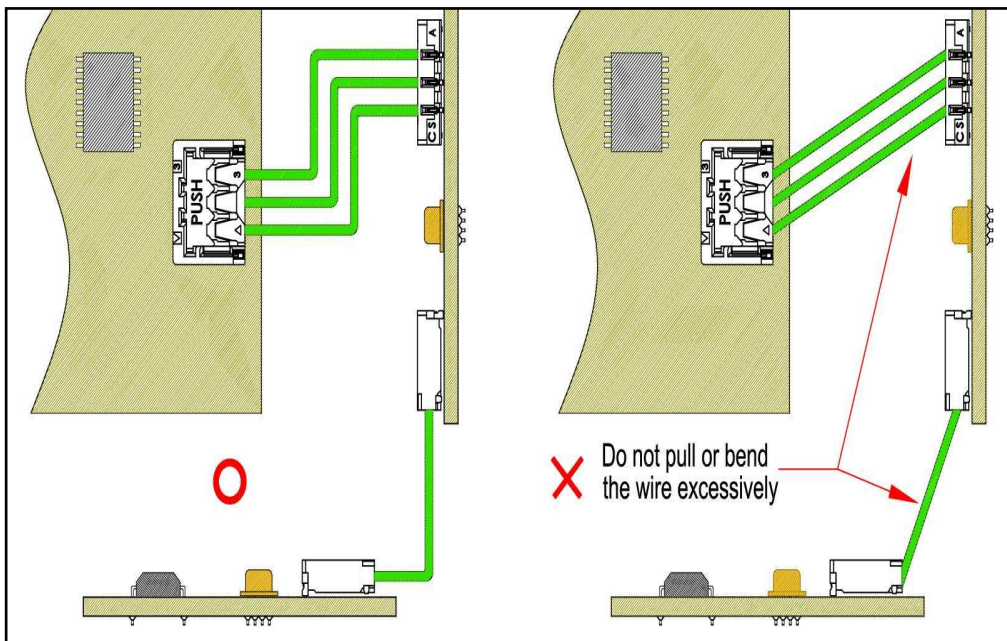


figure 5.1

Reviewed: J.M.Chang **Approved:** Peter Chang **Verified:** Indiana Huang